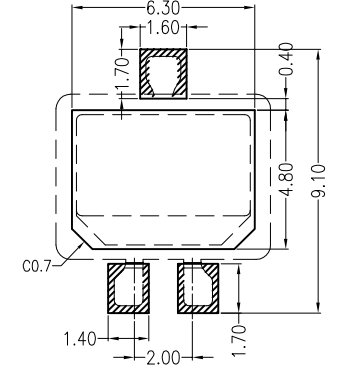
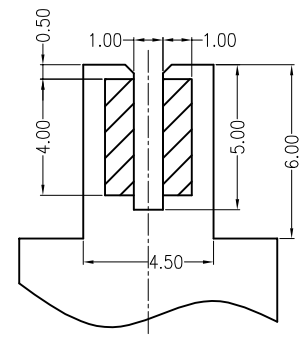
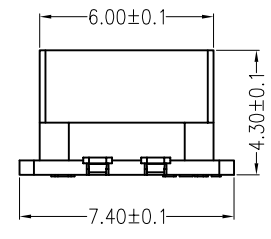
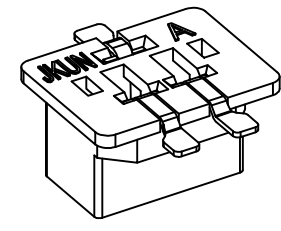
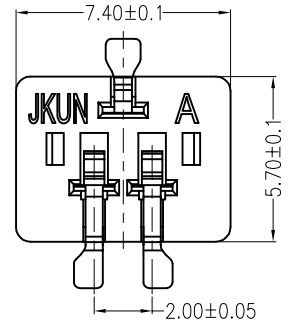
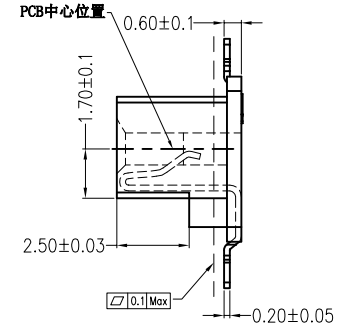
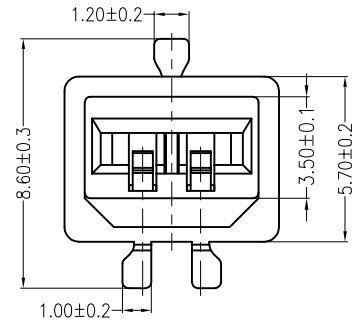


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



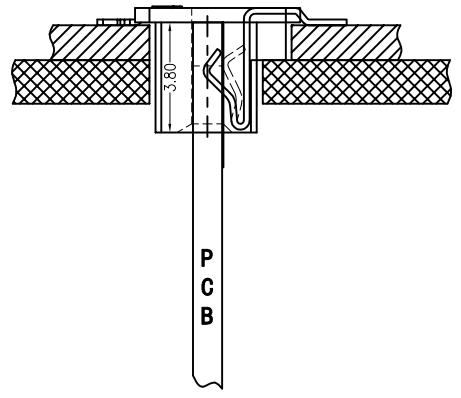
主要技术参数 Main Specifications

- 板 厚 (thickness): 1.0mm
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 1000M\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐 电压 (Withstand Voltage): 800V AC/minute
- 温度范围 (Temperature Range): $-40^{\circ}C \sim +120^{\circ}C$

ORDER INFORMATION:

L038-02-F2MB-R

PART No.		PACKAGING:
No. FOR CIRCUITS:		P=PE
02		R=REEL
PLASTIC MATERIAL:		PLATING:
F2M=LCP (BEIGE)		B=MATTE Sn



Assembly Layout

Mating PCB detail

Board Layout

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	Solder Tab	1 PCS	Brass	MATTE Sn-plated
B	CONTACT	2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TITLE: -
2.0mmPITCH 180°WAFER SMT TYPE

X.±0.5	X.±5'	USE: CUSTOMER	PART NO.: L038-02-F2MB-R
.X±0.3	.X±2'		
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.: JKUN/GCCP-0063
--	--	CHKD: 田峰	SCALE 1 : 1
UNITS: mm		DR: 周秀龙	SHEET 1 / 1